

ABSTRACT OF THE DISCLOSURE

A die bonding method and apparatus that performs bonding position detection and bonding inspection without lowering the productivity, in which after a bonding head has bonded a semiconductor chip to an island, the bonding head is moved to a wafer to pick up a semiconductor chip and is returned to the island; and during this period, an island used for bonding inspection (that is the island on which bonding has just been performed) and an island used for position detection (that is the island on which bonding is to be done next) are imaged by a camera in the same visual field, and inspection of the bonding conditions of the island used for inspection and detection of the position of the island used for position detection are performed based on the acquired image data.